

IN THE CLAIMS:

1. (Currently Amended) A physical vapor deposition chamber for depositing material on a wafer, comprising:

a chuck comprising a planar upper surface and sidewalls extending downwardly therefrom;

a removable, detachable pedestal slip cover overlying the planar upper surface of the chuck and extending laterally beyond the sidewalls and below the planar upper surface along a portion of the sidewall providing a slippable detachment of the slip cover, the removable, detachable pedestal slip cover having a first planar surface and a second planar surface parallel to and located below the first surface the removable, detachable pedestal slip cover having a peripheral circumferential groove in an upper surface of the second surface and a concave lower surface for receiving the planar upper surface of the chuck therein, wherein a circumference of a wafer when positioned on the chuck extends radially inwardly of an inner sidewall of the groove; and

wherein a planar backside of the wafer is in contact with a planar upper surface of the removable, detachable pedestal slip cover during material deposition.

2. (Original) The physical vapor deposition chamber of claim 1 wherein the pedestal cover further comprises a plurality of pads on an upper surface thereof, such that the wafer may be disposed on the plurality of pads

3. (Original) The physical vapor deposition chamber of claim 1 further comprising an aluminum target for depositing aluminum on the wafer.
4. (Previously Presented) The physical vapor deposition chamber of Claim 1, wherein the groove has a width and a depth and the width is greater than the depth.
5. (Previously Presented) The physical vapor deposition chamber of claim 4 wherein the pedestal cover further comprises a plurality of pads on the first planar surface of the removable pedestal cover, such that the wafer may be disposed on the plurality of pads.
6. (Canceled)
7. (Canceled)
8. (Previously Presented) The physical vapor deposition chamber of claim 1 wherein a material of the pedestal cover comprises stainless steel.
9. (Previously Presented) The physical vapor deposition chamber of claim 1 wherein the material of the material deposition process is deposited on the pedestal cover during the material deposition process and is removable therefrom.

10. (Canceled)

11. (Canceled)

12. (Canceled)

13. (Canceled)

14. (Withdrawn) A process for depositing material on a wafer;
providing a chuck;
disposing a pedestal cover over an upper surface of the chuck, the cover defining a
peripheral circumferential trench therein;
disposing a wafer in contact with an upper surface of the cover, the trench spaced radially
outwardly from a circumference of the wafer; and
depositing material on the wafer during which material is deposited in the trench.